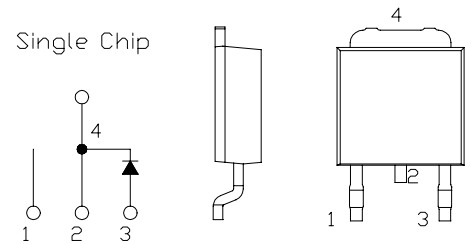


# SBD Type : EA30QS09-F

OUTLINE DRAWING

## FEATURES

- \* TO-252AA Case, Surface Mounting Device
- \* Low Forward Voltage drop
- \* Low Power Loss
- \* High Surge Capability
- \* 40 Volts thru 100 Volts Types Available
- \* Packaged in 16mm Tape and Reel



## Maximum Ratings

Approx Net Weight:0.30g

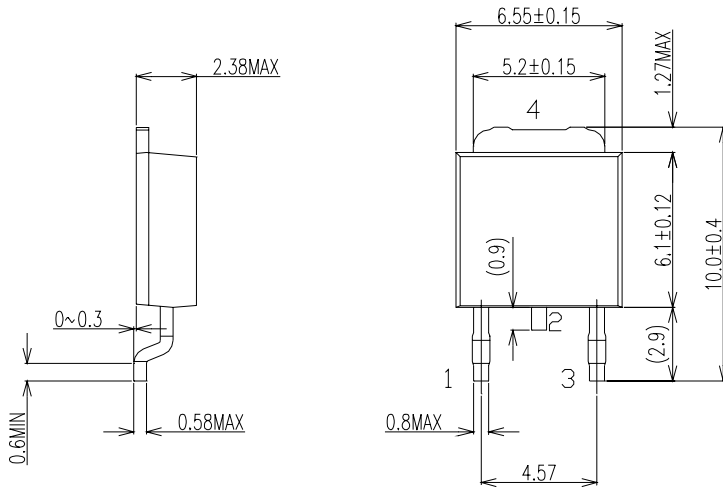
Rating		Symbol	EA30QS09-F			Unit
Repetitive Peak Reverse Voltage		$V_{RRM}$	90			V
Average Rectified Output Current	P.C.Board mounted *	$I_O$	1.6	$T_a=38^{\circ}\text{C}$	50Hz Half Sine Wave Resistive Load	A
	-		3.0	$T_c=133^{\circ}\text{C}$		
RMS Forward Current		$I_{F(RMS)}$	4.71			A
Surge Forward Current		$I_{FSM}$	45	50Hz Half Sine Wave, 1cycle, Non-repetitive		A
Operating Junction Temperature Range		$T_{jw}$	- 40 to + 150			$^{\circ}\text{C}$
Storage Temperature Range		$T_{stg}$	- 40 to + 150			$^{\circ}\text{C}$

## Electrical • Thermal Characteristics

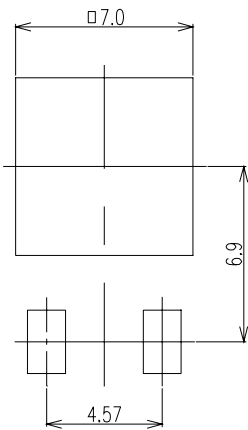
Characteristics		Symbol	Conditions	Min	Typ	Max	Unit
Peak Reverse Current		$I_{RM}$	$T_j=25^{\circ}\text{C}, V_{RM}=V_{RRM}$	-	-	1.0	mA
Peak Forward Voltage		$V_{FM}$	$T_j=25^{\circ}\text{C}, I_{FM}= 3 \text{ A}$	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	P.C.Board mounted *	-	-	80	$^{\circ}\text{C}/\text{W}$
	Junction to Case	$R_{th(j-c)}$	-	-	-	6	$^{\circ}\text{C}/\text{W}$

\* Print Land = 20x20 mm

EA30QS09-F OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD



Single Chip

